



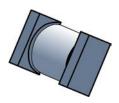
# 3 Amp SQ-MELF Schottky Barrier Rectifiers

Qualified per MIL-PRF-19500/620

Qualified Levels\*: JAN, JANTX, JANTXV and JANS

#### **DESCRIPTION**

This series of 3 amp Schottky rectifiers are compact in their square MELF packaging for high density mounting. The 1N5822US and 1N6864US are military qualified for high-reliability applications.



"B" SQ-MELF (D-5B) Package

Also available in:

**B" Package** (axial-leaded)
1N5820 – 1N5822, 1N6864

Important: For the latest information, visit our website <a href="http://www.microsemi.com">http://www.microsemi.com</a>.

#### **FEATURES**

- JEDEC registered surface mount equivalents of 1N5820 1N5822 and 1N6864 numbers.
- Hermetically sealed.
- Metallurgically bonded.
- Double plug construction.
- \*JAN, JANTX, JANTXV and JANS qualifications are available per MIL-PRF-19500/620 for 1N6822US and 1N6864US only.
   (See <u>Part Nomenclature</u> for all available options.)
- RoHS compliant devices available (commercial grade only on the 1N6822US and 1N6864US).

#### **APPLICATIONS / BENEFITS**

- Small size for high density mounting (see package illustration).
- Non-sensitive to ESD per MIL-STD-750 method 1020.

#### **MAXIMUM RATINGS** @ $T_A = +25$ °C unless otherwise noted.

Parameters/Test Conditions	Symbol	Value	Unit
Junction Temperature	TJ	-65 to +125	°C
Storage Temperature	T <sub>STG</sub>	-65 to +150	°C
Thermal Resistance Junction-to-End Cap	R <sub>OJEC</sub>	10	°C/W
Surge Peak Forward Current @ T <sub>A</sub> = +25 °C	I <sub>FSM</sub>	80	Α
(Test pulse = 8.3 ms, half-sine wave.)			(pk)
Average Rectified Output Current @ T <sub>EC</sub> = +55 °C (1)	Io	3	Α

NOTES: 1. See Figures 3 and 4 for derating curves and for effects of V<sub>R</sub> on T<sub>J</sub>. The maximum T<sub>J</sub> depends on the voltage applied.

MSC - Lawrence

6 Lake Street, Lawrence, MA 01841 1-800-446-1158 Tel: (978) 620-2600

Fax: (978) 689-0803

#### MSC - Ireland

Gort Road Business Park, Ennis, Co. Clare, Ireland Tel: +353 (0) 65 6840044 Fax: +353 (0) 65 6822298

Website:

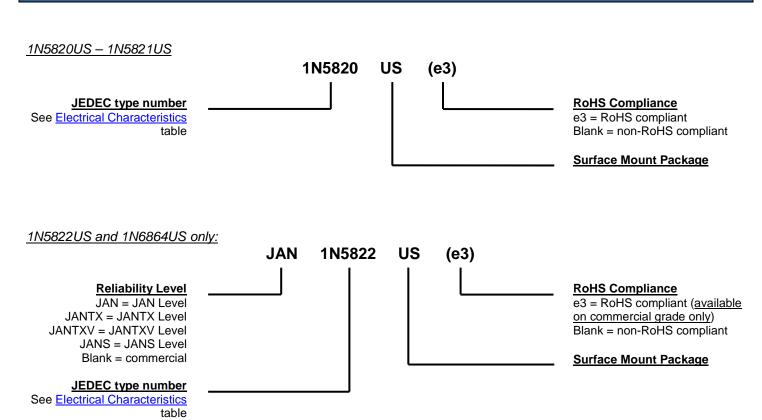
www.microsemi.com



## **MECHANICAL** and PACKAGING

- CASE: Voidless hermetically sealed hard glass.
- TERMINALS: Tin-lead plate with >3% lead. Solder dip is available upon request. RoHS compliant matte-tin is available on commercial levels (no JAN levels).
- MARKING: Body painted and alpha numeric.
- POLARITY: Cathode indicated by band.
- Tape & Reel option: Standard per EIA-481-1-A with 12 mm tape. Consult factory for quantities.
- See <u>Package Dimensions</u> on last page.

### **PART NOMENCLATURE**



	SYMBOLS & DEFINITIONS				
Symbol	Definition				
Ст	Capacitance: The capacitance in pF at a frequency of 1 MHz and specified voltage.				
f	frequency				
I <sub>R</sub>	Maximum Reverse Current: The maximum reverse (leakage) current that will flow at the specified voltage and temperature.				
Io	Average Rectified Output Current: The output current averaged over a full cycle with a 50 Hz or 60 Hz sine-wave input and a 180 degree conduction angle.				
V <sub>F</sub>	Maximum Forward Voltage: The maximum forward voltage the device will exhibit at a specified current.				
V <sub>R</sub>	Reverse Voltage: The dc voltage applied in the reverse direction below the breakdown region.				
V <sub>RWM</sub>	Working Peak Reverse Voltage: The maximum peak voltage that can be applied over the operating temperature range.				



## ELECTRICAL CHARACTERISTICS @ 25 °C unless otherwise noted.

TYPE NUMBER	WORKING PEAK REVERSE VOLTAGE	MAXIMUM FORWARD VOLTAGE V <sub>FM1</sub>	MAXIMUM FORWARD VOLTAGE V <sub>FM2</sub>	MAXIMUM FORWARD VOLTAGE V <sub>FM3</sub>	MAXIMUM REVERSE LEAKAGE CURRENT I <sub>RM</sub> @ V <sub>RM</sub>	
NOMBLIX	V <sub>RWM</sub>	I <sub>FM</sub> = 1.0 A	I <sub>FM</sub> = 3.0 A	I <sub>FM</sub> = 9.4 A	T <sub>J</sub> = +25 °C	T <sub>J</sub> = +100 °C
	V (pk)	Volts	Volts	Volts	mA	mA
1N5820US	20	0.40	0.50	0.70	0.10 @ 20 V	12.5 @ 20 V
1N5821US	30	0.40	0.50	0.70	0.10 @ 30 V	12.5 @ 30 V
1N5822US	40	0.40	0.50	0.70	0.10 @ 40 V	12.5 @ 40 V
1N6864US	80	0.50	0.70	N/A	0.15 @ 80 V	18.0 @ 80 V



### **GRAPHS**

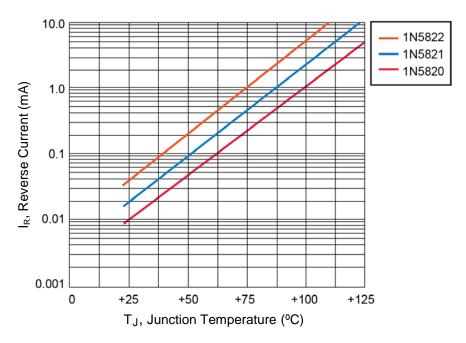


FIGURE 1
Typical Reverse Leakage Current at Rated PIV (PULSED)

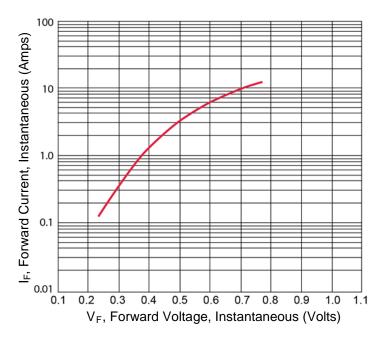
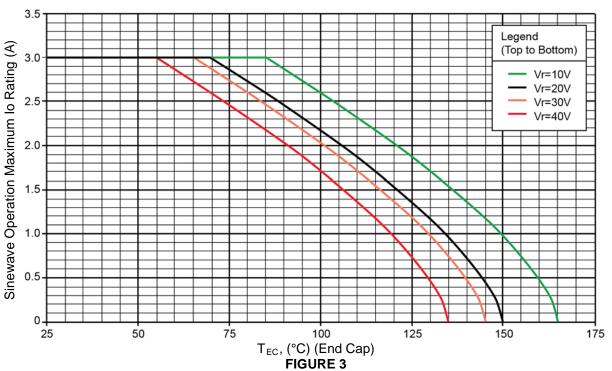


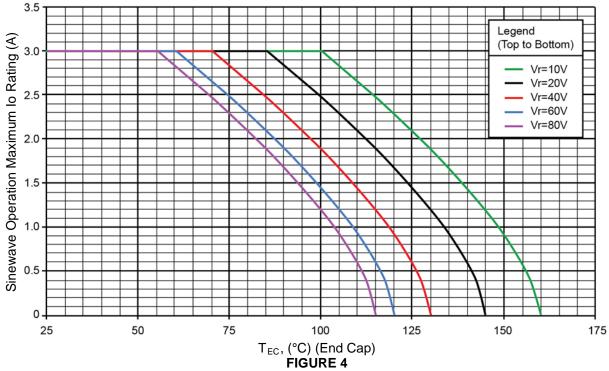
FIGURE 2
Typical Forward Voltage



# **GRAPHS** (continued)

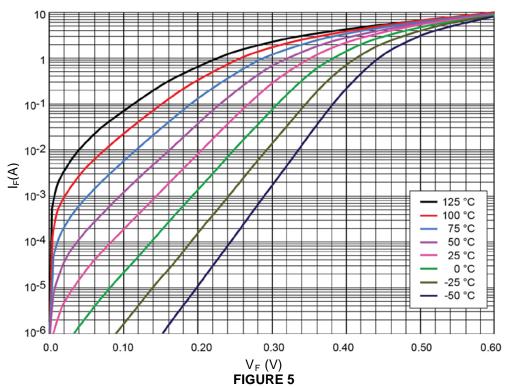


Temperature Current Derating For 1N5822US

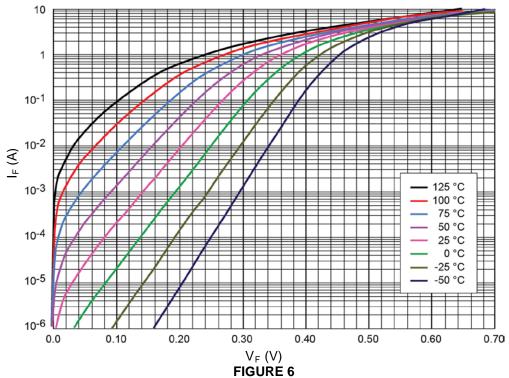


Temperature Current Derating For 1N6864US

# **GRAPHS** (continued)



Schottky V<sub>F</sub> – I<sub>F</sub> Characteristics (Typical 1N5822US)



Schottky V<sub>F</sub> – I<sub>F</sub> Characteristics (Typical 1N6864US)



# **GRAPHS** (continued)

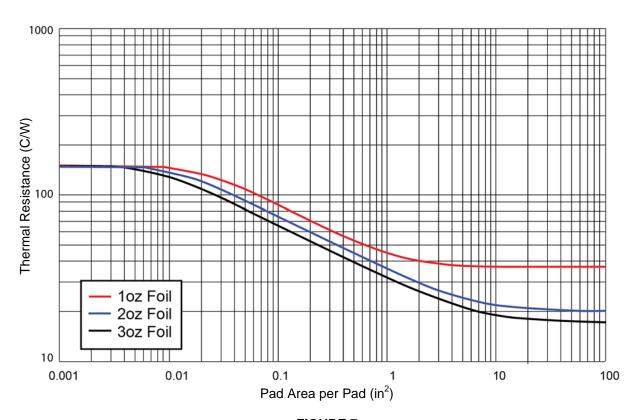
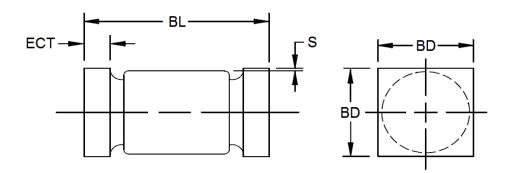


FIGURE 7
Thermal Resistance vs FR4 Pad Area Still Air with the PCB horizontal



## **PACKAGE DIMENSIONS**



	IN	СН	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
BD	0.137	0.148	3.48	3.76	
ECT	0.019	0.028	0.48	0.71	
BL	0.200	0.225	5.08	5.72	
S	0.003 MIN.		0.08 MIN.		

### NOTES:

- 1. Dimensions are in inches. Millimeters are given for information only.
- 2. Dimensions are pre-solder dip.
- 3. U-suffix parts are structurally identical to the US-suffix parts.
- 4. In accordance with ASME Y14.5M, diameters are equivalent to Φx symbology.